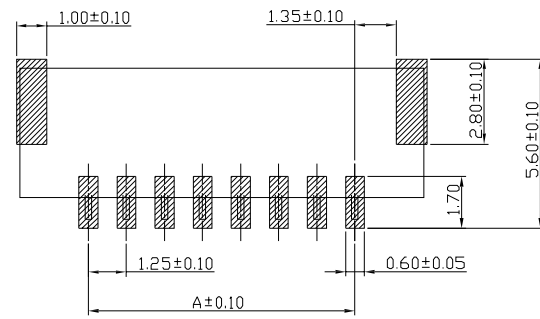
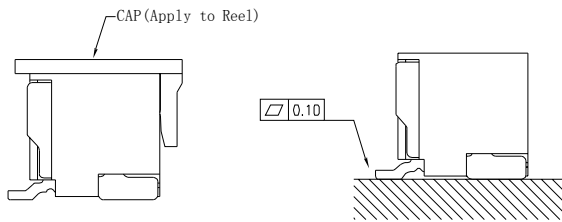
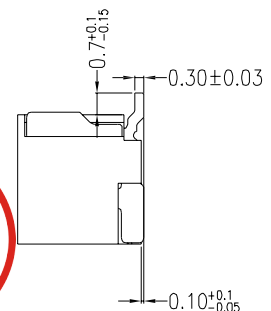
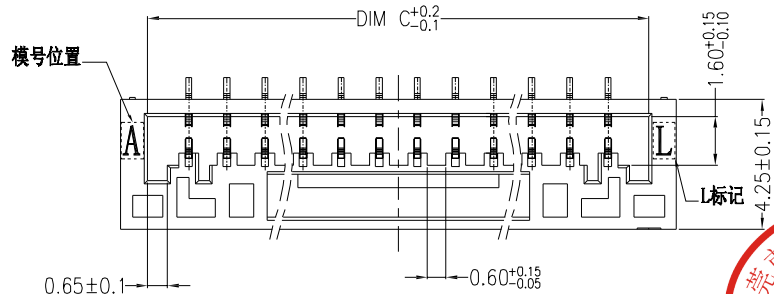
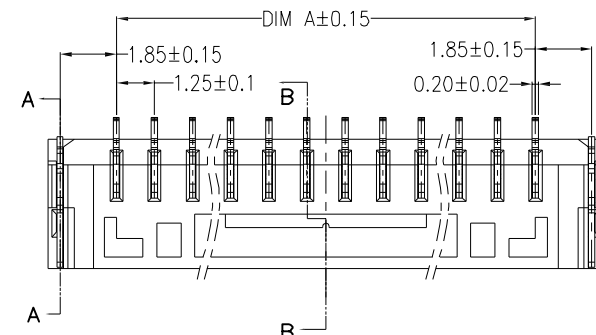
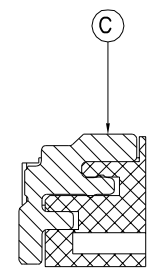
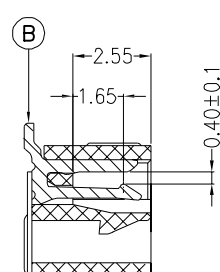
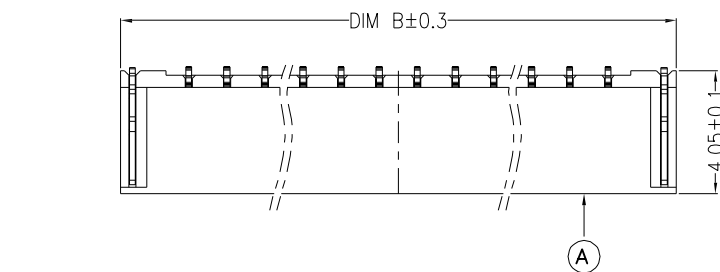




SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

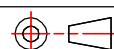
孔位	尺寸	DIM A	DIM B	DIM C	孔位	尺寸	DIM A	DIM B	DIM C
2P	1.25	5.75	3.95	9P	10.00	14.50	12.70		
3P	2.50	7.00	5.20	10P	11.25	15.75	13.95		
4P	3.75	8.25	6.45	11P	12.50	17.00	15.20		
5P	5.00	9.50	7.70	12P	13.75	18.25	16.45		
6P	6.25	10.75	8.95	13P	15.00	19.50	17.70		
7P	7.50	12.00	10.20	14P	16.25	20.75	18.95		
8P	8.75	13.25	11.45	15P	17.50	22.00	20.20		



主要技术参数 Main Specifications

线 数 (Poles): 02 to 15
接触电阻 (Contact resistance): $\leq 20m\Omega$
绝缘电阻 (Insulation resistance): $\geq 100M\Omega$
额定电压 (Rated voltage): 50V AC DC
额定电流 (Rated current): 1.0A AC DC
耐 电 压 (Withstand Voltage): 500V AC/minute
温度范围 (Temperature Range): $-40^{\circ}C \sim +110^{\circ}C$

NO.	DESCRIPTION	QTY	MATERIAL	PLATING/COLOR
A	Insulator	1	LCP (UL94V-0)	Beige
B	Contacts	2~15	PhosphorBronze	Tin-plated
C	Solder Tab	2	PhosphorBronze	Tin-plated

UNITS mm	东莞市朗纶电子制品有限公司 Dongguan langlun electronic products Co., Ltd			
MAT'L				
FINISH	PART NO.(INTENDED USE) GH1.25-nAB	TITLE: GH1.25 立贴插座		
	APPD:	DWG NO.: GH1.25-nAB		
Q'TY PCS	CHKD:	 SCALE: 1/1 SHEET: 1/1 REV: A		
	DR: HU 2016.09.28			